

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of forming a conductive device, the method comprising:

forming a first and second conductive layers on first and second sides, respectively,
of a substrate;

etching the first conductive layer to form a plurality of conductive traces;

etching the first conductive layer to form at least one mask feature;

etching the second conductive layer to define a ground plane; and

removing substrate material that is not covered by the at least one mask feature
so as to form at least one mechanical alignment feature;

wherein the conductive traces and the ground plane form part of the conductive
device.

2. (Currently Amended) The method of claim 1 wherein the etching steps
performed on the first conductive layer are performed simultaneously.

3. (Original) The method of claim 1 wherein the removing step includes
removing the substrate material with a laser.

4. (Original) The method of claim 1 wherein the removing step includes
removing the substrate material so as to form at least one aperture.

5. (Original) The method of claim 1 wherein the removing step includes
removing the substrate material so as to form at least one side edge.

6. (Original) The method of claim 1 wherein the removing step includes
removing the substrate material so as to form at least one tab.

7. (Original) The method of claim 1 wherein the removing step includes removing the substrate material so as to form at least one slot.

8. (Original) A conductive device produced according to the method of claim 1.

9. (Currently Amended) A method of forming a printed circuit board, the method comprising:

forming a first and second conductive layers on first and second opposite sides, respectively, of a substrate;

etching the first conductive layer to form multiple spaced apart conductive traces, each trace having a contact portion,

etching the first conductive layer to form multiple mask features that cooperate to define a template;

etching the second conductive layer to define a ground plane that includes multiple ground contact portions; and

ablating with a laser substrate material that is not covered by the template so as to form a plurality of mechanical alignment features;

wherein the conductive traces and the ground plane form part of the printed circuit board.

10. (Original) The method of claim 9 wherein the etching steps are performed simultaneously.

11. (Previously Amended) The method of claim 9 wherein the ablating step comprises ablating substrate material so as to form multiple apertures and multiple side edges, wherein the apertures and the side edges function as mechanical alignment features.

12. (Original) A printed circuit board produced according to the method of claim 9.

13. (Previously Added) The method of claim 1 wherein the at least one mask feature includes at least one U-shaped mask feature.

14. (Previously Added) The method of claim 1 wherein the at least one mechanical alignment feature includes at least one rectangular tab.

15. (Previously Added) The method of claim 1 wherein the at least one mechanical alignment feature includes at least one rectangular slot.

16. (Previously Added) The method of claim 9 wherein the ablating step comprises positioning a beam of the laser normal to the surface of the substrate having the conductive traces and mask features formed thereon.

17. (Previously Added) The method of claim 9 wherein the multiple mask features include multiple U-shaped mask features.

18. (Previously Added) The method of claim 9 wherein the plurality of mechanical alignment features includes multiple tabs.

19. (Previously Added) The method of claim 9 wherein the plurality of mechanical alignment features includes multiple rectangular tabs.

20. (Previously Added) The method of claim 9 wherein the plurality of mechanical alignment features includes multiple rectangular slots.

21. (New) The method of claim 9 wherein the etching steps performed on the first conductive layer are performed simultaneously such that the method provides precise registration of the mechanical alignment features with the conductive traces.

22. (New) A method of forming a conductive device, the method comprising:
forming a conductive layer on a substrate;

etching the conductive layer to form a plurality of conductive traces;
etching the conductive layer to form at least one mask feature; and
removing substrate material that is not covered by the at least one mask feature
so as to form at least one mechanical alignment feature, wherein the at least one alignment
feature includes at least one tab.

21

23. (New) The method of claim 22 wherein the at least one tab includes at least
one rectangular tab.